OPTIGA™ TPM SLB9672 TPM 2.0 FW15.xx

Datasheet

Trusted Platform Module

Document release reference: Z8F80723106-A

Key features

- Compliant with TCG TPM Library specification revision 1.59 and PC Client Platform TPM Profile (PTP) version 1.05
- PQC-protected firmware update mechanism
- Certifications:
  - Common Criteria, level EAL4+, AVA_VAN.4 (moderate) according to TCG PC Client TPM Protection Profile (targeted) – (2 October 2024) – Certificate number CC-1244
  - FIPS 140-2 Level 2 — (24 October 2022) — Certificate Number 4347
- SPI interface
- Meeting Intel TXT and Microsoft Windows certification criteria for successful platform qualification
- Random Number Generator (RNG) implemented according to NIST SP 800-90A using entropy source according to NIST SP 800-90B
- Provisioned with 3 Endorsement Keys (EK) and EK certificates (RSA 2048, ECC NIST P256, ECC NIST P384)
- Standard (-20..+85°C) and Enhanced temperature range (-40..+85°C)
- PG-UQFN-32-1,-2 package
- Optimized for battery operated devices: low standby power consumption (typ. 120 µA)
- 24 PCRs (SHA-1, SHA-256 or SHA384)
- 51 kByte NV memory
- Unlimited amount of NV counters (only depending on NV memory utilization)
- Up to 3 loaded sessions (TPM_PT_HR_LOADED_MIN)
- Up to 64 active sessions (TPM_PT_ACTIVE_SESSIONS_MAX)
- Up to 3 loaded transient Objects (TPM_PT_HR_TRANSIENT_MIN)
- Up to 7 loaded persistent Objects (TPM_PT_HR_PERSISTENT_MIN)
- Pre-generation of up to 7 RSA key pairs
- RSA (1024, 2048, 3072 and 4096 bit)
- ECC (NIST P256, NIST P384, BN P256)
- SHA-1, SHA-256, SHA-384
- AES-128, AES-256

Product validation

Qualified for applications according to the test conditions in the relevant tests of JEDEC JESD22 and J-STD-020.

Ordering information

Device name	Package	Remarks
SLB 9672VU2.0 FW15.xx	PG-UQFN-32-1,-2	Standard temperature range -20°C - 85°C
SLB 9672XU2.0 FW15.xx	PG-UQFN-32-1,-2	Enhanced temperature range -40°C - 85°C

About this document

Scope and purpose

This datasheet describes the SLB 9672 TPM 2.0 FW15.xx Trusted Platform Module together with its features, functionality and programming interface.

Intended audience

This datasheet is primarily intended for system developers.

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1 Introduction

1.1 Product description

The SLB 9672 TPM 2.0 is a Trusted Platform Module. It is available in PG-UQFN-32-1,-2 package. It supports an SPI interface with a transfer rate of up to 33 MHz (typical). The SLB 9672 TPM 2.0 is compliant with TCG TPM Library specification revision 1.59 [1] and PC Client Platform TPM Profile (PTP) version 1.05 [2], including Errata (see [3] and [4]).

This TPM product is targeted to be certified, using the Common Criteria for Information Technology Security Evaluation (CC), Version 3.1 Rev.5, in the level EAL4+, AVA_VAN.4 (moderate), ALC_FLR.1 according to the Protection Profile PC Client Specific TPM, TPM Library Specification Family "2.0" Level 0 Revision 1.59 (CERTIFICATE ANSSI-CC-PP-2020/01).

1.2 Power management

In the SLB 9672 TPM 2.0, power management is handled internally; no explicit power-down or standby mode is available. The device automatically enters a low-power state after each successful command/response transaction. If a transaction is started on the SPI bus from the host platform, the device will wake up immediately and will return to the low-power mode after the transaction has been finished.

2 Delivery forms and ordering

The SLB 9672 TPM 2.0 product family features devices using an UQFN package.

2.1 Package dimensions (UQFN)

All dimensions are given in millimeters (mm) unless otherwise noted. The packages are "green" and RoHS compliant.

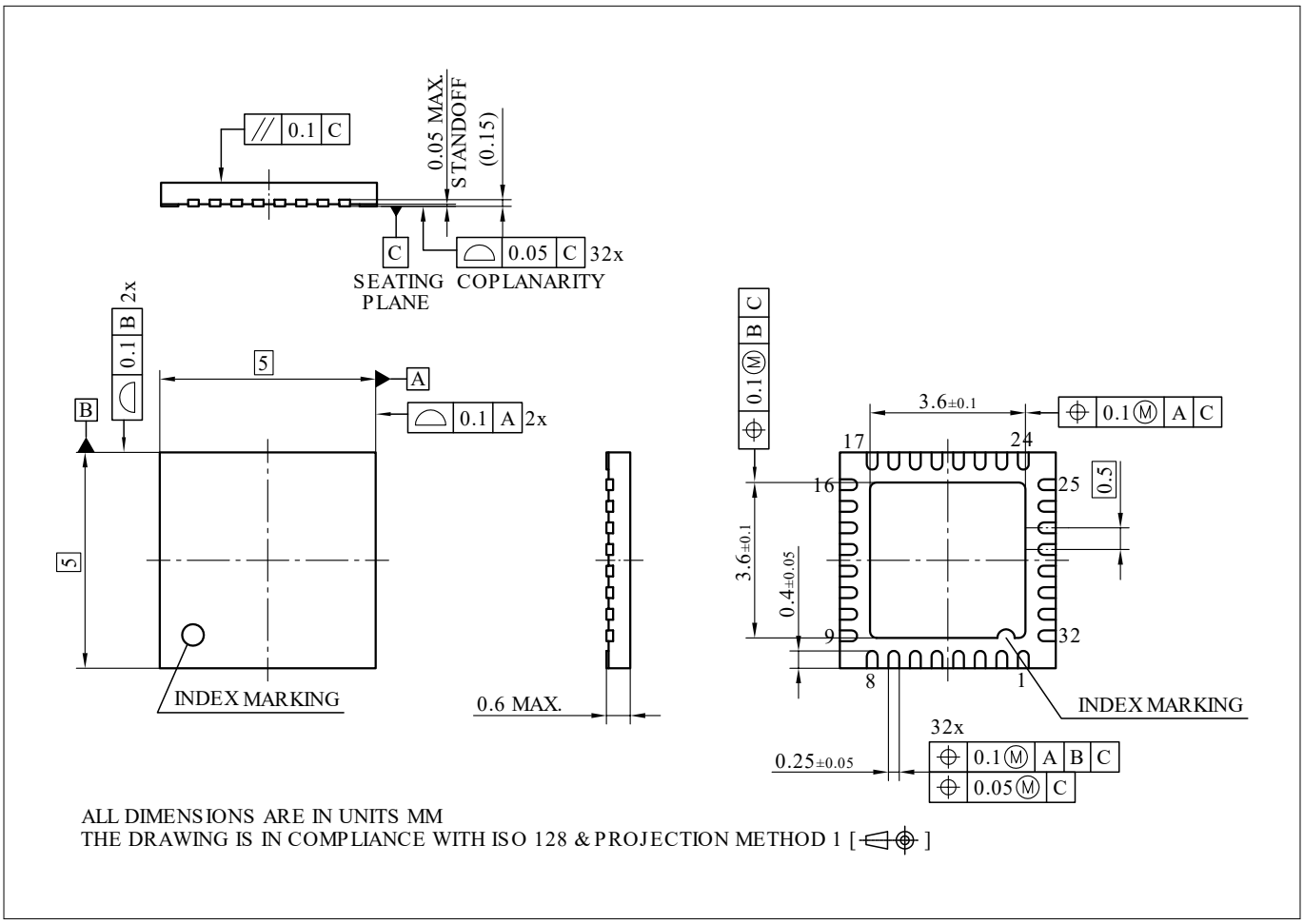


Figure 1 Package dimensions PG-UQFN-32-1,-2

2.1.1 Packing type

PG-UQFN-32-1,-2: Tape & Reel (reel diameter 330mm), 5000 pcs. per reel

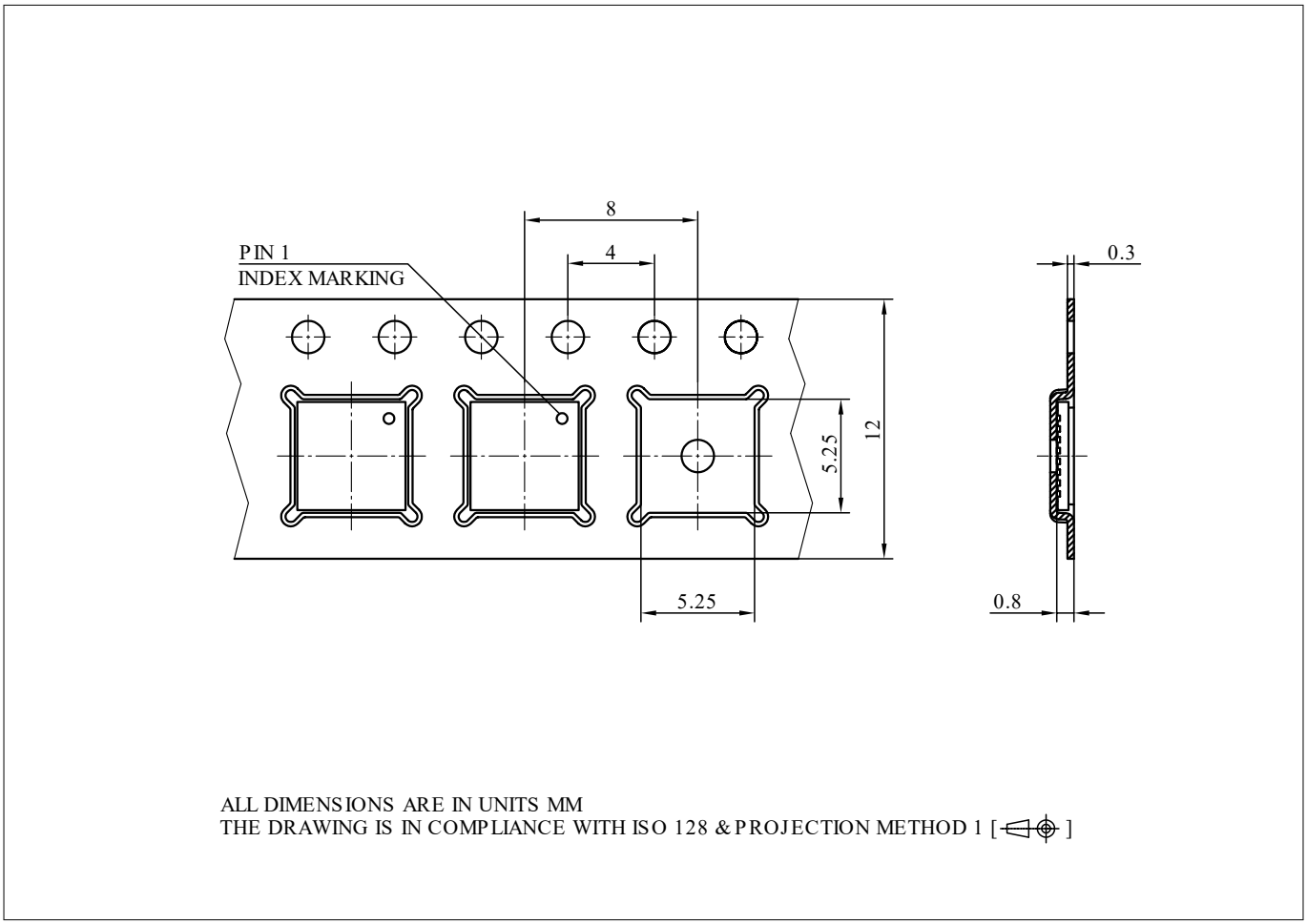


Figure 2 Tape & reel dimensions PG-UQFN-32-1,-2

2.1.2 Recommended footprint

The figure below shows the recommended footprint for the PG-UQFN-32-1,-2 package. The exposed pad of the package is internally connected to GND. It shall be connected to GND externally as well.

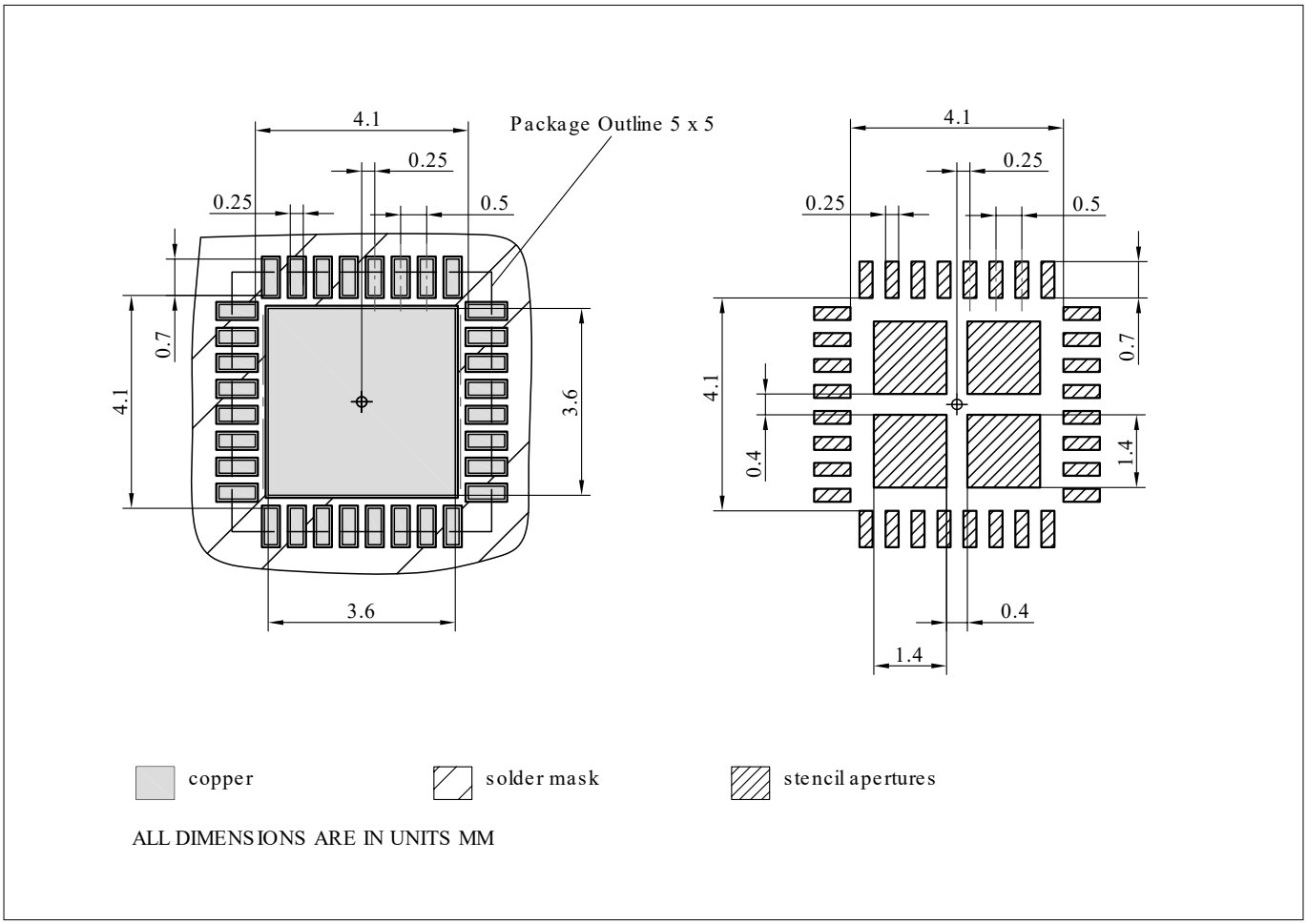


Figure 3 Recommended footprint PG-UQFN-32-1,-2

2.1.3 Chip marking

Line 1: SLB 9672

Line 2: VU20 yy or XU20 yy (see Ordering information), the <yy> is an internal FW indication (only at manufacturing due to field upgrade option)

Line 3: <Lot number> H <datecode>, the <datecode> is given as year (YY) and calendar week (CW)

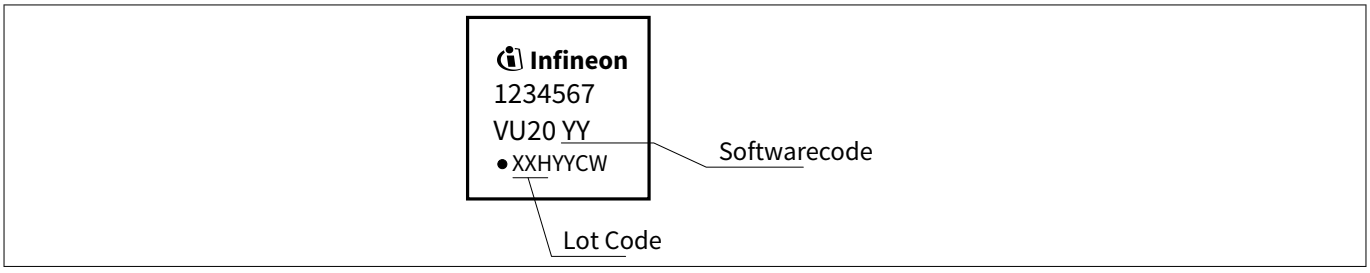


Figure 4 Chip marking

For details and recommendations regarding assembly of packages on PCBs, please refer to https://www.infineon.com/cms/en/product/packages/

2.2 Ordering information

Table 1 Sales order code

Sales code (Sales name/ Product)	Ordering code	Software code	Status
SLB 9672VU2.0 FW15.12	SP005555413	07	Discontinued
SLB 9672XU2.0 FW15.12	SP005555415	07	Discontinued
SLB 9672VU2.0 FW15.20	SP005563106	08	Discontinued
SLB 9672XU2.0 FW15.20	SP005563108	08	Discontinued
SLB 9672VU2.0 FW15.20	SP005574386	16	Discontinued
SLB 9672XU2.0 FW15.20	SP005574388	16	Discontinued
SLB 9672VU2.0 FW15.21	SP005594740	17	Discontinued (end of 2024)
SLB 9672XU2.0 FW15.21	SP005594742	17	Discontinued (end of 2024)
SLB 9672VU2.0 FW15.22	SP005750307	22	Discontinued (end of 2024)
SLB 9672XU2.0 FW15.22	SP005750320	22	Discontinued (end of 2024)
SLB 9672VU2.0 FW15.23	SP005919740	25	Active
SLB 9672XU2.0 FW15.23	SP005919742	26	Active
SLB 9672VU2.0 FW15.24	SP006026245	42	Active
SLB 9672XU2.0 FW15.24	SP006026262	42	Active

3 Solution details

3.1 Hardware

3.1.1 Electrical characteristics

This chapter lists the maximum and operating ranges for various electrical and timing parameters.

3.1.1.1 Absolute maximum ratings

Table 2 Absolute maximum ratings

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Supply Voltage	V_{DD}	-0.3	–	4.1	V	–
Voltage on any pin	V_{max}	-0.5	–	4.1	V	–
Ambient temperature	T_A	-20	–	85	°C	Standard temperature SLB 9672VU2.0 devices
Ambient temperature	T_A	-40	–	85	°C	Enhanced temperature SLB 9672XU2.0 devices
Storage temperature	T_S	-40	–	125	°C	–
ESD robustness HBM: 1.5 kΩ, 100 pF	$V_{ESD,HBM}$	–	–	2000	V	According to EIA/JESD22-A114-B
ESD robustness	$V_{ESD,CDM}$	–	–	500	V	According to ESD Association Standard STM5.3.1 - 1999
Latchup immunity	I_{latch}			100	mA	According to EIA/JESD78

Attention**: **Stresses above the maximum values listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Maximum ratings are absolute ratings; exceeding only one of these values may cause irreversible damage to the integrated circuit.

3.1.1.2 Functional operating range

Table 3 Functional operating range

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Supply Voltage	V_{DD}	3.0	3.3	3.6	V	–
		1.65	1.8	1.95	V	–
Ambient temperature	T_A	-20	–	85	°C	Standard temperature SLB 9672VU2.0 devices
Ambient temperature	T_A	-40	–	85	°C	Enhanced temperature SLB 9672XU2.0 devices
Useful lifetime		–	–	10	y	
Operating lifetime		–	–	10	y	
Average T_A over lifetime		–	55	–	°C	

3.1.1.3 DC characteristics

T_A = 25°C, V_{DD} = 3.3 V ± 0.3 V or V_{DD} = 1.8 V ± 0.15 V unless otherwise noted.

Table 4 Current consumption

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Current Consumption in Active Mode	I_{VDD_Active}			35	mA	
Current Consumption in Sleep Mode	I_{VDD_Sleep}		120		µA	Pins GPIO, RST# and PIRQ# = V_{DD} , CS# inactive (= V_{DD}), MOSI, MISO and SCLK don't care
Current Consumption during reset	I_{VDD_Reset}		130		µA	Pin RST# active (= GND), GPIO, PIRQ#, CS#, MOSI, MISO and SCLK don't care

***Note**: Current consumption does not include any currents flowing through resistive loads on output pins!*

***Note**: Device sleep mode will be entered after 50 milliseconds of inactivity after the last TPM command was executed.*

Table 5 DC characteristics of SPI interface pins (SCLK, CS#, MISO, MOSI, RST#, PIRQ#)

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Input voltage high	V_{IH}	0.7 V_{DD}		V_{DD}+0.5	V	$V_{DD,typ}$ = 3.3 V, only pins SCLK, MISO, MOSI and CS#
		0.7 V_{DD}		V_{DD}+0.3	V	$V_{DD,typ}$ = 3.3 V, pin RST#
		0.7 V_{DD}		V_{DD}+0.3	V	$V_{DD,typ}$ = 1.8 V
Input voltage low	V_{IL}	-0.5		0.3 V_{DD}	V	$V_{DD,typ}$ = 3.3 V
		-0.3		0.3 V_{DD}	V	$V_{DD,typ}$ = 1.8 V
Input leakage current	I_{LEAK}	-4		4	µA	*0 V* < V_{IN} < V_{DD}
		-4.5			mA	Pins SCLK, CS#, MISO, MOSI -0.5 V < V_{IN} < V_{DD} +0.5 V $V_{DD,typ}$ = 3.3 V
		-4.5			mA	Pins SCLK, CS#, MISO, MOSI -0.3 V < V_{IN} < V_{DD} +0.3 V $V_{DD,typ}$ = 1.8 V
		-2		2	µA	Pin RST# 0 V < V_{IN} < V_{DD}
Output high voltage	V_{OH}	0.9 V_{DD}			V	I_{OH} = -100 µA
Output low voltage	V_{OL}			0.1 V_{DD}	V	I_{OL} = 1.5 mA
Pad input capacitance	C_{IN}			10	pF	
Output load capacitance	C_{LOAD}			30	pF	

Table 6 DC characteristics of GPIO pins

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Input voltage high	V_{IH}	0.7 V_{DD}		V_{DD}+0.3	V	Pins GPIO
Input voltage low	V_{IL}	-0.5		0.3 V_{DD}	V	Pins GPIO
Input leakage current	I_{LEAK}	-2		2	µA	0 V < V_{IN} < V_{DD}
Output high voltage	V_{OH}	V_{DD} -0.3			V	I_{OH} = -1 mA, pins GPIO
Output low voltage	V_{OL}			0.3	V	I_{OL} = 1 mA, pins GPIO
Pad input capacitance	C_{IN}			10	pF	Pins GPIO

3.1.1.4 AC characteristics

T_A = 25°C, V_{DD} = 3.3V ± 0.3V or V_{DD} = 1.8V ± 0.15V unless otherwise noted.

Table 7 Power supply

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Supply voltage rise time	t_{VDDR}			1.0	V/ns	

Table 8 Device reset

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Cold (Power-On) Reset	t_{POR}	80			µs	
Warm Reset	t_{WRST}	2			µs	

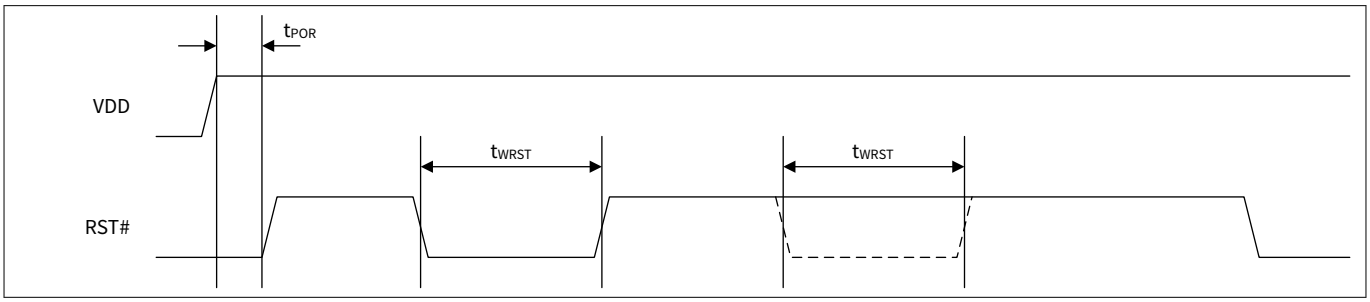


Figure 5 Reset timing

Table 9 AC characteristics of SPI interface

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
SCLK frequency	f_{CLK}		33	34.65	MHz	
SCLK period	t_{CLK}	1/f_{CLK} - 5%	1/f_{CLK}	1/f_{CLK} + 5%	µs	Rising edge to rising edge, measured at V_{IN} = 0.5 V_{DD}
SCLK low time	t_{CLKL}	0.45 t_{CLK}			µs	Falling edge to rising edge, measured at V_{IN} = 0.5 V_{DD}

(table continues...)

Table 9 (continued) AC characteristics of SPI interface

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
SCLK high time	t_{CLKH}	0.45 t_{CLK}			µs	Rising edge to falling edge, measured at V_{IN} = 0.5 V_{DD}
SCLK slew rate (rising/ falling)	t_{SLEW}	0.1		4	V/ns	f_{CLK} ≤ 20 MHz, between 0.2 V_{DD} and 0.6 V_{DD}
		0.27		4	V/ns	f_{CLK} > 20 MHz, between 0.2 V_{DD} and 0.6 V_{DD}
CS# high time	t_{CS}	50			ns	Rising edge to falling edge
		60			ns	$V_{DD,typ}$ = 1.8 V and t_{SLEW} < 1 V/ns, rising edge to falling edge, TPM protocol abort only
CS# setup time	t_{CSS}	5			ns	CS# falling edge to SCLK rising edge
		7			ns	$V_{DD,typ}$ = 1.8 V and t_{SLEW} < 1 V/ns, CS# falling edge to SCLK rising edge
CS# hold time	t_{CSH}	5			ns	SCLK falling edge to CS# rising edge
MOSI setup time	t_{SU}	2			ns	Data setup time to SCLK rising edge
MOSI hold time	t_{H}	3			ns	Data hold time from SCLK rising edge
MISO hold time	t_{HO}	0			ns	Output hold time from SCLK falling edge
MISO valid delay time	t_{V}	0		0.7 t_{CLKL}	ns	Output valid delay from SCLK falling edge
MISO active time	t_{DRV}	0			ns	Delay from chip select assertion to driving of MISO

3.1.1.5 Timing

Some pads are disabled after deassertion of the reset signal for up to 500 µs.
The SLB 9672 TPM 2.0 features security mechanisms which detect and count all resets.

3.1.2 Pin description

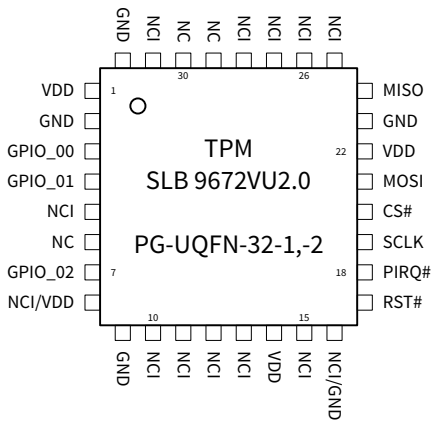


Figure 6 Pinout of the SLB 9672 TPM 2.0 (PG-UQFN-32-1,-2 package, top view)

Table 10 Buffer types

Buffer type	Description
TS	Tri-state pin
IN	Input pin
OD	Open-drain pin

Table 11 I/O Signals

Pin number PG-UQFN-32-1,-2	Name	Pin type	Buffer type	Function
20	CS#	I	IN	Chip select The SPI chip select signal (active low).
19	SCLK	I	IN	SPI clock The SPI clock signal. Only SPI mode 0 is supported by the device.
21	MOSI	I	IN	Master out slave in (SPI data) SPI data which is received from the master.
24	MISO	O	TS	Master in slave out (SPI data) SPI data which is sent to the SPI bus master.
18	PIRQ#	O	OD	Interrupt request Interrupt request signal to the host. The pin has no internal pull-up resistor. The interrupt is active low.
17	RST#	I	IN	Reset External reset signal. Asserting this pin unconditionally resets the device. The signal is active low and is typically connected to the PCIRST# signal of the host. This pin has a weak internal pull-up resistor.

(table continues...)

Table 11 (continued) I/O Signals

Pin number PG-UQFN-32-1,-2	Name	Pin type	Buffer type	Function
3	GPIO_00	I/O	TS	General purpose IO This pin may be left unconnected; it has an internal pull-up resistor. It can be controlled via TPM NV GPIO functionality.
4	GPIO_01	I/O	TS	General purpose IO This pin may be left unconnected; it has an internal pull-up resistor. It can be controlled via TPM NV GPIO functionality.
7	GPIO_02	I/O	TS	General purpose IO This pin may be left unconnected; it has an internal pull-up resistor. It can be controlled via TPM NV GPIO functionality.

Table 12 Power supply

Pin number PG-UQFN-32-1,-2	Name	Pin type	Buffer type	Function
1, 14, 22	VDD	PWR	—	Power supply All VDD pins must be connected externally and should be bypassed to GND via 100 nF capacitors.
2, 9, 23, 32	GND	GND	—	Ground All GND pins must be connected externally.

Table 13 Not connected

Pin number PG-UQFN-32-1,-2	Name	Pin type	Buffer type	Function
6, 29, 30	NC	NU	—	No connect All pins must not be connected externally (must be left floating).
5, 11 - 13, 15, 25 - 28, 31	NCI	—	—	Not connected internally All pins are not connected internally (can be connected externally).
10	NCI/VDD	—	—	Not connected internally This pin is not connected internally. For future use, it is recommended to either connect this pin to VDD via a pull-up resistor (preferred) or to leave this pin unconnected.
8	NCI/VDD	—	—	Not connected internally/VDD This pin is not connected internally (can be connected externally). Note that pin 8 is defined as VDD in the TCG specification [2]. To be compliant, VDD can be connected to this pin. For future use, it is recommended to connect this pin to VDD.

(table continues...)

Table 13 (continued) Not connected

Pin number PG-UQFN-32-1,-2	Name	Pin type	Buffer type	Function
16	NCI/GND	—	—	Not connected internally/GND This pin is not connected internally (can be connected externally). Note that pin 16 is defined as GND in the TCG specification [2]. To be compliant, GND can be connected to this pin. For future use, it is recommended to connect this pin to GND.

3.1.3 Typical schematic

The figure below shows the typical schematic for the SLB 9672 TPM 2.0. The power supply pins should be bypassed to GND with capacitors located close to the device.

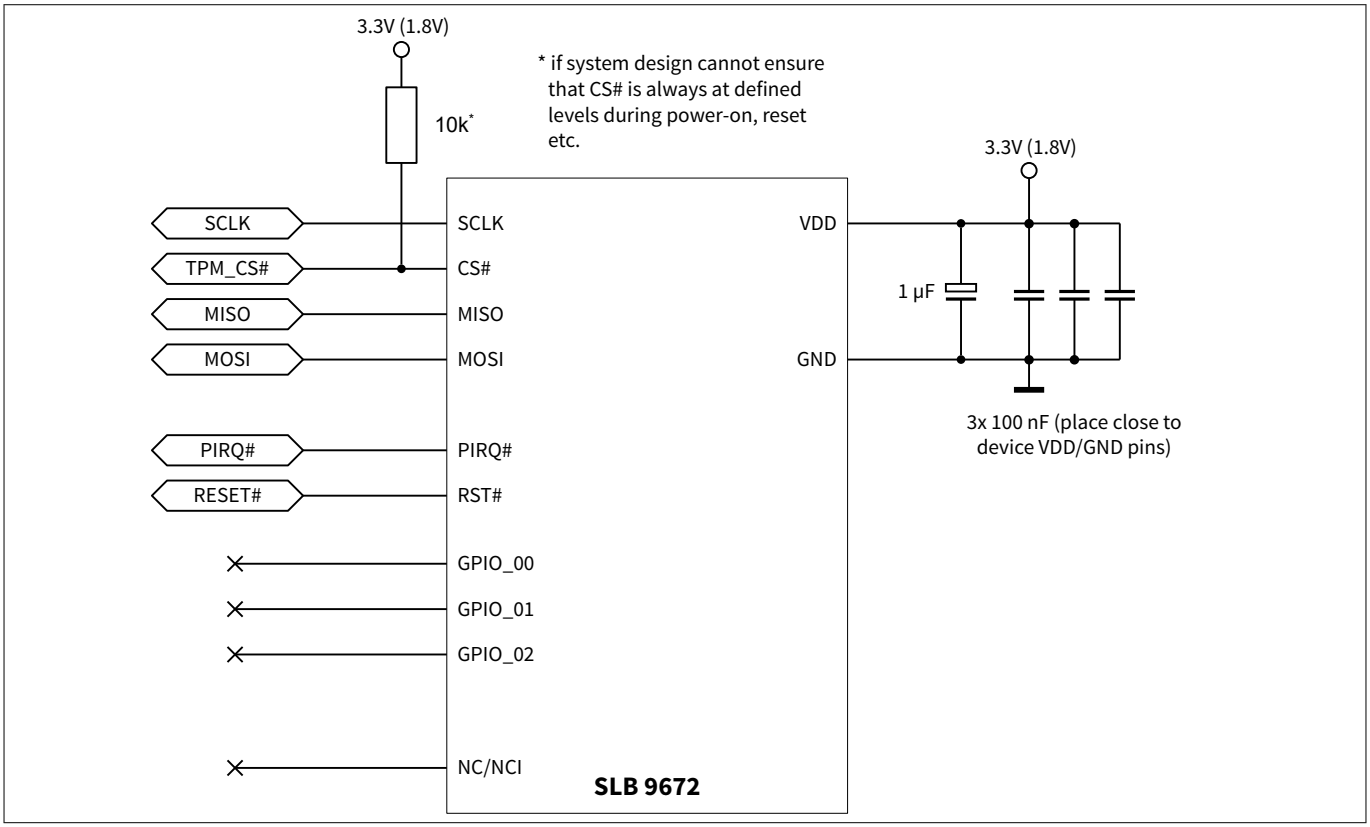


Figure 7 Typical schematic

3.2 TPM embedded software

The embedded software of the Infineon SLB 9672 TPM 2.0 is fully compliant with the TPM Library specification [1] and the PC Client Platform TPM Profile (PTP) [2], including Errata (see [3] and [4]).

This section documents vendor-specific functionality and also the actual parameters of the implementation since the specified values in [1] and [2] are only minimum requirements.

3.2.1 Implemented algorithms

A list of algorithms implemented in the TPM can be read using the TPM2_GetCapability command (capability = TPM_CAP_ALGS).

TPM_ALG_AES supports only CFB mode and may be used for all specified use cases (see [1]) except for bulk encryption via the commands TPM2_EncryptDecrypt or TPM2_EncryptDecrypt2, which are not implemented by this TPM.

The elliptic curve TPM_ECC_BN_P256 can only be used for ECDAA.

Table 14 Implemented algorithms

Algorithm name	Key size/curve	Mandatory (M), optional (O) per [2]	Implemented in SLB 9672 TPM 2.0
TPM_ALG_RSA	1024	SHOULD NOT BE USED	X (D)
	2048	M	X
	3072	M	X
	4096	O	X
TPM_ALG_AES	128	M	X
	256	M	X
TPM_ALG_SHA1	n.a.	M/D	X (D)
TPM_ALG_SHA256	n.a.	M	X
TPM_ALG_SHA384	n.a.	M	X
TPM_ALG_ECC	TPM_ECC_NIST_P256	M	X
	TPM_ECC_NIST_P384	M	X
	TPM_ECC_BN_P256	O	X

***Note**: TPM_ALG_RSA with 1024-bit and TPM_ALG_SHA1 support is implemented but deprecated (D). Consequently, support for these algorithms may be removed in a future version and it is not recommended to use them anymore.*

3.2.2 Available resources

The table below provides an overview of the available resources.

Table 15 Available resources

Number of PCRs (SHA-1, SHA-256 or SHA-384) (TPM_PT_PCR_COUNT) See Allocation of PCR banks for further details.	24
Amount of free NV memory including space of predefined NV indices (3 EK certificates)	51072 Bytes
Amount of free NV memory without space of predefined NV indices (3 EK certificates)	47424 Bytes

(table continues...)

Table 15 (continued) Available resources

Maximum number of loaded sessions (TPM_PT_HR_LOADED_MIN)	3
Maximum number of active sessions (TPM_PT_ACTIVE_SESSIONS_MAX)	64
Maximum number of loaded transient Objects (TPM_PT_HR_TRANSIENT_MIN)	3
Maximum number of loaded persistent Objects (TPM_PT_HR_PERSISTENT_MIN)	7
Maximum number of NV counters (NV Index with TPMA_NV_COUNTER set, TPM_PT_NV_COUNTERS_MAX)	0 [1)]
Minimum number of NV indices with TPM_NT_PIN_FAIL or TPM_NT_PIN_PASS set	2
Maximum parameter size (TPM_PT_INPUT_BUFFER)	1024 Bytes
Maximum data size for NV read or NV write (TPM_PT_NV_BUFFER_MAX)	768 Bytes
Maximum size of an NV index data area (TPM_PT_NV_INDEX_MAX)	2160 Bytes
I/O-Buffer size in TPM operational mode (max. command/response size) TPM_PT_MAX_COMMAND_SIZE TPM_PT_MAX_RESPONSE_SIZE	2000 Bytes
I/O-Buffer size in TPM firmware update mode (max. command/response size) TPM_PT_MAX_COMMAND_SIZE TPM_PT_MAX_RESPONSE_SIZE	1100 Bytes

1) The value 0 indicates that there is no fixed maximum. The number of counter indices is determined by the available NV memory pool.

3.2.3 Command ordinal list

The TPM implements the TCG standard commands defined in Table 16 and the vendor-specific commands defined in Table 17. All other ordinals will return TPM_RC_COMMAND_CODE.

Table 16 Command code list

Signals	
_TPM_INIT	_TPM_HashData
_TPM_HashStart	_TPM_HashEnd
Startup	
TPM_CC_Startup	TPM_CC_Shutdown
Testing	
TPM_CC_IncrementalSelfTest	TPM_CC_SelfTest
TPM_CC_GetTestResult	
Session Commands	
TPM_CC_StartAuthSession	TPM_CC_PolicyRestart
Object Commands	
TPM_CC_Create	TPM_CC_Load
TPM_CC_LoadExternal	TPM_CC_ReadPublic
TPM_CC_ActivateCredential	TPM_CC_MakeCredential
TPM_CC_Unseal	TPM_CC_ObjectChangeAuth
TPM_CC_CreateLoaded	
Duplication Commands	
TPM_CC_Duplicate	TPM_CC_Import
Asymmetric Primitives	
TPM_CC_RSA_Encrypt	TPM_CC_RSA_Decrypt
TPM_CC_ECDH_KeyGen	TPM_CC_ECDH_ZGen
TPM_CC_ECC_Parameters	
Symmetric Primitives	
TPM_CC_Hash	TPM_CC_HMAC
Random Number Generator	
TPM_CC_GetRandom	TPM_CC_StirRandom
Hash/HMAC/Event Sequences	
TPM_CC_HMAC_Start	TPM_CC_HashSequenceStart
TPM_CC_SequenceUpdate	TPM_CC_SequenceComplete
TPM_CC_EventSequenceComplete	
Attestation Commands	
TPM_CC_Certify	TPM_CC_CertifyCreation
TPM_CC_Quote	TPM_CC_GetSessionAuditDigest
TPM_CC_GetTime	

(table continues...)

Table 16 (continued) Command code list

Anonymous Attestation	
TPM_CC_Commit	
Signature Verification	
TPM_CC_VerifySignature	TPM_CC_Sign
Integrity Collection (PCR)	
TPM_CC_PCR_Extend	TPM_CC_PCR_Event
TPM_CC_PCR_Read	TPM_CC_PCR_Allocate
TPM_CC_PCR_Reset	
Enhanced Authorization (EA) Commands	
TPM_CC_PolicySigned	TPM_CC_PolicySecret
TPM_CC_PolicyTicket	TPM_CC_PolicyOR
TPM_CC_PolicyPCR	TPM_CC_PolicyLocality
TPM_CC_PolicyNV	TPM_CC_PolicyCounterTimer
TPM_CC_PolicyCommandCode	TPM_CC_PolicyCpHash
TPM_CC_PolicyNameHash	TPM_CC_PolicyDuplicationSelect
TPM_CC_PolicyAuthorize	TPM_CC_PolicyAuthValue
TPM_CC_PolicyPassword	TPM_CC_PolicyGetDigest
TPM_CC_PolicyNvWritten	TPM_CC_PolicyTemplate
TPM_CC_PolicyAuthorizeNV	
Hierarchy Commands	
TPM_CC_CreatePrimary	TPM_CC_HierarchyControl
TPM_CC_SetPrimaryPolicy	TPM_CC_ChangePPS
TPM_CC_ChangeEPS	TPM_CC_Clear
TPM_CC_ClearControl	TPM_CC_HierarchyChangeAuth
Dictionary Attack Functions	
TPM_CC_DictionaryAttackLockReset	TPM_CC_DictionaryAttackParameters
Context Management	
TPM_CC_ContextSave	TPM_CC_ContextLoad
TPM_CC_FlushContext	TPM_CC_EvictControl
Clocks and Timers	
TPM_CC_ReadClock	TPM_CC_ClockSet
TPM_CC_ClockRateAdjust	
Capability Commands	
TPM_CC_GetCapability	TPM_CC_TestParms
Non-Volatile Storage	
TPM_CC_NV_DefineSpace	TPM_CC_NV_UndefineSpace
TPM_CC_NV_UndefineSpaceSpecial	TPM_CC_NV_ReadPublic

(table continues...)

Table 16 (continued) Command code list

TPM_CC_NV_Write	TPM_CC_NV_Increment
TPM_CC_NV_Extend	TPM_CC_NV_SetBits
TPM_CC_NV_WriteLock	TPM_CC_NV_Read
TPM_CC_NV_ReadLock	TPM_CC_NV_ChangeAuth
TPM_CC_NV_Certify	

***Note**: Table 17 does not comprehensively list all vendor-defined TPM commands.*

Table 17 Vendor-specific TPM_CC constants

Name	Command code	NV write	Decrypt	Encrypt	Description
TPM_CC_FullFipsSelfTestVendor	0x20000401	N	N	N	Vendor specific command for executing all selftests which are performed at first power-up. Refer to TPM2_FullFipsSelfTestVendor for further details.
TPM_CC_FieldUpgradeStartVendor	0x2000012F	Y	N	N	Vendor specific command for starting TPM firmware update mode while in TPM operational mode. Refer to TPM2_FieldUpgradeStartVendor for further details.
TPM_CC_FieldUpgradeAbandonVendor	0x20000130	N	N	N	Vendor specific command for aborting the field upgrade while in TPM firmware update mode. Refer to TPM2_FieldUpgradeAbandonVendor for further details.
TPM_CC_FieldUpgradeManifestVendor	0x20000131	Y	N	N	Vendor specific command for validating the manifest while in TPM firmware update mode. Refer to TPM2_FieldUpgradeManifestVendor for further details.

(table continues...)

Table 17 (continued) Vendor-specific TPM_CC constants

Name	Command code	NV write	Decrypt	Encrypt	Description
TPM_CC_FieldUpgradeDataVendor	0x20000132	Y	N	N	Vendor specific command for updating the firmware while in TPM firmware update mode. Refer to TPM2_FieldUpgradeDataVendor for further details.
TPM_CC_FieldUpgradeFinalizeVendor	0x20000133	Y	N	N	Vendor-specific command for finalizing the field upgrade process in TPM operational mode. Refer to TPM2_FieldUpgradeFinalizeVendor for further details.

3.2.4 Generation of RSA keys

3.2.4.1 Pre-generation of RSA keys

The TPM provides pre-generation of 2048-bit RSA keys in the background during idle times. A maximum of seven 2048-bit RSA keys can be generated and stored in non-volatile memory without any impact on the available amount of free non-volatile memory as stated in Table 15. When the user instructs the TPM to generate a new 2048-bit ordinary RSA key using TPM2_Create or TPM2_CreateLoaded, one of the pre-generated keys (if available) will be picked and returned. If the user demands more keys than the number of currently available pre- generated keys, the TPM will need to generate new keys in place, which will increase the total response time. All pre-generated keys will be discarded if command TPM2_StirRandom is sent to the TPM and reseeding of TPM Random Number Generator (RNG) is triggered.

Pre-generation is only supported for (RSA 2k) Ordinary keys. Pre-generation of Primary and Derived keys are not supported because their generation depends on caller-provided data. Pre-generation of any key types other than RSA is not supported because there is no performance advantage.

***Note**: The key pre-generation is activated after TPM2_SelfTest has been executed after a reset (_TPM_INIT). Pre-generation of RSA 3072- and 4096-bit keys is not supported.*

3.2.4.2 Generation of RSA 3072- and 4096-bit keys

The creation of a 3072- or 4096-bit RSA primary key may take several minutes. For this reason, the duration of TPM2_CreatePrimary may violate the configured driver timeout value when waiting for the response of TPM2_CreatePrimary. For example, the Linux Kernel v4.17 or higher uses a timeout value of 300 seconds for TPM2_CreatePrimary. This value may also be violated in some cases.

For Windows 10 or 11, when using a 3072-bit RSA key, update the following key if it exists in the registry editor:

[HKEY_LOCAL_MACHINE\SYSTEM\CurrentControlSet\Services\TPM]

"TimeoutCommandCreate" = dword:02000000

3.2.5 Non-volatile storage

3.2.5.1 Predefined NV indices

The sizes documented in Table 18 are typical values and may vary by some bytes. The actual size can be read from the TPM using the command TPM2_NV_ReadPublic where parameter nvIndex defines the certificate whose size is to be determined.

***Note**: The validity period of the EK certificate spans 15 years starting with production. This covers the validity for an expected lifetime of 10 years plus a buffer of 5 years between production and TPM assembly.*

Table 18 Predefined NV indices

Value	Index Name	Default Size	Attributes
0x01C00002	RSA 2048 EK Certificate	1427 bytes (RSA Endorsement Key Certificate)	see Table 19
0x01C0000A	ECC NIST P256 EK Certificate	844 bytes (ECC Endorsement Key Certificate)	see Table 19
0x01C00016	ECC NIST P384 EK Certificate	873 bytes (ECC Endorsement Key Certificate)	see Table 19

Table 19 Attributes of predefined NV indices

Attributes
TPMA_NV_PPWRITE
TPMA_NV_WRITEDEFINE
TPMA_NV_PPREAD
TPMA_NV_OWNERREAD
TPMA_NV_AUTHREAD
TPMA_NV_NO_DA
TPMA_NV_WRITTEN
TPMA_NV_PLATFORMCREATE

3.2.6 Vendor-specific functionality

This section describes vendor-specific functionality, such as vendor-specific properties, commands and default values/settings, which extends the functionality described in the TPM Library specification [1].

3.2.6.1 Power saving mode

The TPM supports a reduced power consumption mode which is entered after inactivity for at least 50 ms has been detected. The resulting power consumption in this mode is shown in Table 4 (current consumption in sleep mode).

3.2.6.2 TPM and vendor properties

Properties defined within the TPM can be read with the command TPM2_GetCapability. The values are vendor dependent or determined by a platform-specific specification. The following properties are returned by the Infineon SLB 9672 TPM 2.0 using the command TPM2_GetCapability (capability = TPM_CAP_TPM_PROPERTIES):

Table 20 Infineon TPM property values

TPM_PT_MANUFACTURER	“IFX”
TPM_PT_VENDOR_STRING_1	“SLB9”
TPM_PT_VENDOR_STRING_2	“672”
TPM_PT_VENDOR_STRING_3	NULL
TPM_PT_VENDOR_STRING_4	NULL
TPM_PT_FIRMWARE_VERSION_1	Major and minor version (for instance, 0x000F0018 indicates V15.24) [1)]
TPM_PT_FIRMWARE_VERSION_2	Build number and Common Criteria certification state (for instance, 0x004A0A00 or 0x004A0A02)[1)] Byte 1: reserved for future use (0x00) Byte 2 and 3: Build number (for instance, 0x4A0A)[1)] Byte 4: Common Criteria certification state/mode: 0x00 = TPM operational mode/TPM is CC certified 0x02 = TPM operational mode/TPM is not certified 0x62 = TPM firmware update mode
TPM_PT_MODES	Bit 0 (FIPS_140_2) = 1 Bits 1..31 = 0

1) The build- and version numbers given here are examples and do not necessarily match the numbers of the device this datasheet has been provided for.

The vendor-specific properties shown in the table below can be read by using the vendor-specific capability selector TPM_CAP_VENDOR_PROPERTIES:

Table 21 Infineon vendor-specific property constants

TPM property	Value	Property value
PT_VENDOR_FIX	0x80000000	The group of fixed vendor specific properties.
PT_VENDOR_VAR	0xC0000000	The group of variable vendor specific properties.

Table 22 Infineon vendor-specific property values

TPM property	Value	Property value
TPM_PT_VENDOR_FIX_FU_COUNTER	PT_VENDOR_FIX + 3	UINT16 field upgrade counter for upgrades to different firmware version
TPM_PT_VENDOR_FIX_FU_COUNTER_SAME	PT_VENDOR_FIX + 4	UINT16 field upgrade counter for upgrades to same firmware version
TPM_PT_VENDOR_FIX_FU_START_HASH_DIGEST	PT_VENDOR_FIX + 5	TPMT_HA structure containing manifest hash digest for field upgrade: Bytes 1-2: Hash digest algorithm (TPM_ALG_SHA384, TPM_ALG_SHA512) Bytes 3-66: SHA512 manifest digest or Bytes 3-50: SHA384 manifest digest or
TPM_PT_VENDOR_FIX_FU_OPERATION_MODE	PT_VENDOR_FIX + 7	UINT8 operation mode of firmware as described in Table 23
TPM_PT_VENDOR_FIX_FU_KEYGROUP_ID	PT_VENDOR_FIX + 8	UINT32 ID of field upgrade keys

An overview of all possible values returned for the operation mode is given in the following table:

Table 23 TPM operation modes

Operation Mode	Description
0x00	Normal TPM operational mode
0x01	TPM firmware update mode when abandoning the field upgrade process is possible
0x02	TPM firmware update mode when abandoning the field upgrade process is not possible anymore
0x03	After successful field upgrade, but before TPM2_FieldUpgradeFinalizeVendor
0x04	After TPM2_FieldUpgradeFinalizeVendor or TPM2_FieldUpgradeAbandonVendor until the next reboot

The next table lists FIFO Configuration registers initialized by the vendor.

Table 24 FIFO configuration registers

Register	Value	Comments
TPM_VID	0x15d1	Vendor identification of Infineon Technologies AG
TPM_DID	0x001d	Device identification
TPM_RID	0x36	Revision identification register

Table 25 TPM_RID register value description

Bit	Description
0	TPM 1.2 if set
1	TPM 2.0 if set
2	FIPS if set
3	Reserved for future use, value 0
4-7	Interface revision, currently 0011_B

3.2.6.3 Selftest operations

3.2.6.3.1 TPM2_SelfTest

This command executes all selftests except for the tests which are only performed at first power-up (see Table 28 for further details). The selftest can be done in two ways. TPM2_Selftest(fullTest = YES) always performs all tests while TPM2_Selftest(fullTest = NO) only executes tests which have not been run yet.

3.2.6.3.2 TPM2_FullFipsSelfTestVendor

This command executes on demand all selftests which are performed at first power-up as required by FIPS 140-2. The selftest result can be read using the command TPM2_GetTestResult.

Table 26 Incoming operands and sizes

Type	Name	Description
TPMI_ST_COMMAND_TAG	tag	TPM_ST_NO_SESSIONS
UINT32	commandSize	
TPM_CC	commandCode	TPM_CC_FullFipsSelfTestVendor

Table 27 Outgoing operands and sizes

Type	Name	Description
TPM_ST	tag	
UINT32	responseSize	
TPM_RC	responseCode	

3.2.6.3.3 TPM2_GetTestResult

The TPM will return to the caller with outData = 11 bytes consisting of

- 4 bytes: a bit field describing the result of the passed selftests
- 4 bytes: a bit-field describing the not yet executed selftests
- 2 bytes: internal information
- 1 byte: operation mode (see Table 23)

The mapping of the individual bits to the corresponding selftest which is executed by the command TPM2_SelfTest is shown in Table 28 below. The bit mapping of the selftests performed by TPM2_FullFipsSelfTestVendor is listed in Table 29 (bit == 1 means that the test passed, RFU bits are reserved for future use).

Table 28 TPM2_SelfTest bit mapping of TPM2_SelfTest

Bit	Meaning	Bit	Meaning
31-21	RFU	10	RFU
20	AES128	9	RSA PKCS1 2048
19-16	RFU	8-6	RFU
15	Sensortest	5	SHA384
14	RFU	4	RFU
13	TPM Firmware Integrity App Partial	3	SHA1
12	RFU	2-1	RFU

(table continues...)

Table 28 (continued) TPM2_SelfTest bit mapping of TPM2_SelfTest

Bit	Meaning	Bit	Meaning
11	TRNG	0	ECC Sign

Table 29 TPM2_SelfTest bit mapping of TPM2_FullFipsSelfTestVendor

Bit	Meaning	Bit	Meaning
31-21	RFU	9	RSA PKCS1 2048
20	AES128	8	KDFe
19	RSA PKCS1 3072	7	KDFa SHA256
18-16	RFU	6	RFU
15	Sensortest	5	SHA384
14	TPM Firmware Integrity App Full	4	RFU
13	TPM Firmware Integrity App Partial	3	SHA1
12	TPM Firmware Integrity OS Full	2	ECC ECDH
11	TRNG	1	RFU
10	DRNG	0	ECC Sign

The next table below shows the expected result returned after a successful selftest command:

Table 30 TPM2_SelfTest result

Selftest command	Passed selftests (first 4 bytes of outData) returned by TPM2_GetTestResult
TPM2_FullFipsSelfTestVendor	0x00, 0x18, 0xFF, 0xAD
TPM2_SelfTest	0x00, 0x10, 0xAA, 0x29

3.2.6.4 Dictionary attack default values

Besides other security mechanisms, the TPM 2.0 supports protection against guessing or exhaustive searches of authorization values stored in the device (see [1] for further details). To provide suitable protection, the parameters for this dictionary attack protection need to be chosen carefully. The command TPM2_DictionaryAttackParameters is used to program these values into the TPM. The following parameters are set as factory default:

- maxTries: 32
- recoveryTime: 7200 seconds
- lockoutRecovery: 86400 seconds

3.2.6.5 RSA signing scheme

RSASSA-PSS signing operation uses the digest size for the salt. RSASSA-PSS signature verification may only succeed if the size of the used salt is from 0 to digest size, or equals (key size) - (digest size) - 2.

3.2.6.6 NV index attribute TPMA_NV_WRITTEN

The TPMA_NV_WRITTEN bit is set if an NV index write operation completed successfully; otherwise, it is not set. Additionally, the TPMA_NV_WRITTEN bit is also cleared before writing data to an NV index and only set again if data has been completely written to an NV index.

As a consequence, the TPMA_NV_WRITTEN bit will not be set if a write to a NV index was discontinued (for instance, due to a reset or a power loss of the device during that write operation).

This allows checking the consistency of data of an NV index. If an NV index contains inconsistent data due to a discontinued write operation, the TPMA_NV_WRITTEN bit is 0.

3.2.6.7 Allocation of PCR banks

This TPM supports only one bank of PCRs, default allocation is Hash Algorithm ID 0x000B (SHA256). The TPM2_PCR_Allocate command can be used to change the allocation of the PCR bank as described in [1] Part 1, chapter 17.8 and [1] Part 3, chapter 22.5.

3.2.6.8 General purpose I/O (GPIO)

All GPIO pins described in Table 11 are mapped to ordinary NV indices with the corresponding handle values listed in the table below.

Table 31 Mapping of GPIO indices

GPIO name	TPM_NV_INDEX
GPIO_00	0x01C40000
GPIO_01	0x01C40001
GPIO_02	0x01C40002

The NV GPIO functionality complies with [2], section 4.5.4.1 General Purpose I/O (GPIO). The TPM NV commands are used to access the NV GPIO pins.

3.2.6.8.1 TPM2_NV_DefineSpace

Before a NV GPIO pin can be used, an NV Index must be defined with TPM2_NV_DefineSpace:

- nvIndex handle must be set to a handle value in Table 31
- dataSize must be 1
- index type must be TPM_NT_ORDINARY
- attribute TPMA_NV_WRITEALL must be CLEAR

If TPMA_NV_CLEAR_STCLEAR is CLEAR, the written GPIO state is preserved across TPM Reset and TPM Restart.

***Note**: All other NV index attributes have the same meaning as for a conventional NV Index.*

3.2.6.8.2 TPM2_NV_Write

TPM2_NV_Write will configure the GPIO pin as output pin and set the pin value:

- write 1 byte at offset 0
- data = 1 will set the GPIO output to high level (1)
- data = 0 will set the GPIO output to low level (0)

***Note**: data > 1 will also set the GPIO output to high level (1).*

3.2.6.8.3 TPM2_NV_Read

TPM2_NV_Read will configure the GPIO pin as input pin and read the pin value:

- read 1 byte at offset 0
- data = 1 means the GPIO input is at high level (1)
- data = 0 means the GPIO input is at low level (0)

***Note**: Reading the GPIO NV index will succeed even if TPMA_NV_WRITTEN is CLEAR.*

3.2.6.8.4 TPM2_NV_UndefineSpace

TPM2_NV_UndefineSpace will undefine the NV index used to access the GPIO pin. After TPM2_UndefineSpace, the GPIO pin is in the same state as after power on. The GPIO state is set to ‘off’ with a weak pullup.

3.2.6.9 Field upgrade

The SLB 9672 TPM 2.0 has two different modes of operation. One mode is the normal TPM operational mode with the capability to execute all TPM 2.0 commands, the other mode is the TPM firmware update mode in which the capabilities of the TPM 2.0 are limited to those commands necessary to perform a successful field upgrade.

After successfully executing the TPM2_FieldUpgradeStartVendor command, the SLB 9672 TPM 2.0 transitions from normal TPM operational mode to TPM firmware update mode.Once in the mode for updating TPM firmware, the manifest has to be transmitted using TPM2_FieldUpgradeManifestVendor. The size of a typical manifest necessitates multiple calls to TPM2_FieldUpgradeManifestVendor. After sending the complete manifest, the TPM2_FieldUpgradeDataVendor command must be invoked as many times as required to send the entire field upgrade image in multiple blocks. After the firmware has been completely updated, the command TPM2_FieldUpgradeFinalzeVendor completes the field upgrade process and returns the TPM to its operational mode. During TPM firmware update mode, the TPM 2.0 standard command format is used.

The TPM field upgrade protected capability is divided into several commands. The next sections list these different commands.

If the field upgrade process is not completed successfully (hence leaving an invalid TPM firmware), the TPM enters failure mode. After a reboot, the command sequence to execute the field upgrade process again will be allowed starting with the command TPM2_FieldUpgradeManifestVendor.

The TPM is provided with two counters (field upgrade counters), which limit the number of field upgrade attempts. A total maximum of 1256 field upgrades is possible. For field upgrades to the same firmware version an additional constraint of 256 attempts applies. The number of counted attempts for field upgrades to the same version is reset when field upgrade to a newer version was applied. Interrupted or failed upgrades will increment the field upgrade counters as well. When one of the counters reaches its maximum, no further field upgrade to any firmware version or to the same firmware version is possible and the command TPM2_FieldUpgradeManifestVendor will return 'TPM_RC_FAILURE'. Care should be taken during the last available attempt: if interrupted, the TPM will remain in TPM firmware update mode and will not be usable anymore.

3.2.6.9.1 Structures and definitions

3.2.6.9.2 TPM2B_MAX_BUFFER_VENDOR

Table 32 TPM2B_MAX_BUFFER_VENDOR structure definition

Type	Name	Description
uint16_t	size	Size of buffer
uint8_t[size]	buffer	Buffer

3.2.6.9.3 TPML_MAX_BUFFER

Table 33 TPML_MAX_BUFFER structure definition

Type	Name	Description
uint32_t	count	Number of properties
TPM2B_MAX_BUFFER_VENDOR	vendorData	List of property values

3.2.6.9.4 Commands in TPM operational mode

TPM2_FieldUpgradeStartVendor

This command can be used to start the field upgrade process.
This command requires authorization with platformPolicy.

***Note**: The command is not available when the TPM is in TPM firmware update mode. After successful execution of the command, the TPM operates in TPM firmware update mode.*

***Note**: A dead time of 300 ms must be considered before sending the first command within TPM firmware update mode.*

Table 34 Incoming operands and sizes

Type	Name	Description
TPMI_ST_COMMAND_TAG	tag	TPM_ST_SESSIONS
UINT32	commandSize	
TPM_CC	commandCode	TPM_CC_FieldUpgradeStartVendor
TPM_RH_PLATFORM	@authorization	TPM_RH_PLATFORM Auth Index: 1 Auth Role: ADMIN
UINT8	type	type that defines the content of data
TPM2B_MAX_BUFFER	data	For type = 0x01: buffer contains a TPMT_HA structure with a hash algorithm and digest value of the manifest

Table 35 Outgoing operands and sizes

Type	Name	Description
TPM_ST	tag	
UINT32	responseSize	
TPM_RC	responseCode	
UINT16	reserved	set to 0x0000

Table 36 Error return codes

Return Code	Meaning
TPM_RC_POLICY_FAIL	A policy check failed
PM_RC_SIZE	The size of the digest is invalid
TPM_RC_VALUE	Type or hash algorithm value is not valid
TPM_RC_HANDLE	The handle is not correct for this usage
TPM_RC_FAILURE	The command failed

***Note**: Other return codes may occur; they are compliant with [1] Part 2, chapter 6.6.*

TPM2_FieldUpgradeFinalizeVendor

This is the last command of the field upgrade process. After execution of this command, a power cycle or a reset cycle is required.

Table 37 Incoming operands and sizes

Type	Name	Description
TPMI_ST_COMMAND_TAG	tag	TPM_ST_NO_SESSIONS
UINT32	commandSize	
TPM_CC	commandCode	TPM_CC_FieldUpgradeFinalizeVendor
TPM2B_MAX_BUFFER	data	Reserved for future use, must be zero

Table 38 Outgoing operands and sizes

Type	Name	Description
TPM_ST	tag	
UINT32	responseSize	
TPM_RC	responseCode	

Table 39 Error return codes

Return Code	Meaning
TPM_RC_BAD_TAG	Incorrect tag
TPM_RC_FAILURE	The command failed
TPM_RC_REBOOT	Indicates that a reboot is required

3.2.6.9.5 Commands in TPM firmware update mode

TPM2_FieldUpgradeManifestVendor

This command validates and processes the manifest and increments the field upgrade counters. It requires that TPM2_FieldUpgradeStartVendor has been executed before. Since the manifest exceeds a limit of 1024 bytes, it must be splitted into chunks of 1024 bytes or smaller. The parameter processingInfo must be used accordingly to signal chained transmission of the manifest.

After successful execution of TPM2_FieldUpgradeManifestVendor aborting the field upgrade process is still possible by executing the command TPM2_FieldUpgradeAbandonVendor. If power loss occurs before sending the first TPM2_FieldUpgradeDataVendor, the field upgrade process can be restarted after a reboot by resending TPM2_FieldUpgradeManifestVendor. Alternatively, it can be aborted after the reboot by TPM2_FieldUpgradeAbandonVendor.

Table 40 Incoming operands and sizes

Type	Name	Description
TPMI_ST_COMMAND_TAG	tag	TPM_ST_NO_SESSIONS
UINT32	commandSize	
TPM_CC	commandCode	TPM_CC_FieldUpgradeManifestVendor
UINT8	processingInfo	0 = last block 1 = first block 2 = consecutive block
TPM2B_MAX_BUFFER	data	Block of the signed manifest

Table 41 Outgoing operands and sizes

Type	Name	Description
TPM_ST	tag	
UINT32	responseSize	
TPM_RC	responseCode	

Table 42 Error return codes

Return Code	Meaning
TPM_RC_COMMAND_SIZE	Incorrect command size
TPM_RC_BAD_TAG	Incorrect tag
TPM_RC_LOCALITY	The locality is not correct
TPM_RC_AUTH_FAIL	Manifest validation failed
TPM_RC_DISABLED	The command has already been executed successfully before
TPM_RC_TOO_MANY_CONTEXTS	TPM2_FieldUpgradeDataVendor has been executed before
TPM_RC_FAILURE	The command failed

TPM2_FieldUpgradeDataVendor

This command shall be called as often as necessary until the complete firmware is upgraded. It requires that either TPM2_FieldUpgradeManifestVendor or TPM2_FieldUpgradeDataVendor has been executed before.

After sending the first TPM2_FieldUpgradeDataVendor the field upgrade process cannot be aborted anymore by the command TPM2_FieldUpgradeAbandonVendor. If power loss occurs after sending the first

TPM2_FieldUpgradeDataVendor, the field upgrade process must be restarted after a reboot by resending TPM2_FieldUpgradeManifestVendor.

***Note**: A dead time of 300 ms should be considered before sending the next command.*

Table 43 Incoming operands and sizes

Type	Name	Description
TPMI_ST_COMMAND_TAG	tag	TPM_ST_NO_SESSIONS
UINT32	commandSize	
TPM_CC	commandCode	TPM_CC_FieldUpgradeDataVendor
TPM2B_MAX_BUFFER	fuData	Encrypted field upgrade image data block

Table 44 Outgoing operands and sizes

Type	Name	Description
TPM_ST	tag	
UINT32	responseSize	
TPM_RC	responseCode	

Table 45 Error return codes

Return Code	Meaning
TPM_RC_COMMAND_SIZE	Incorrect command size
TPM_RC_BAD_TAG	Incorrect tag
TPM_RC_LOCALITY	The locality is not correct
TPM_RC_AUTH_MISSING	Manifest validation using TPM2_FieldUpgradeManifestVendor is required
TPM_RC_FAILURE	The command failed

TPM2_FieldUpgradeAbandonVendor

This command allows aborting the field upgrade process and switching back to the TPM operational mode after a system reset is performed. Aborting the field upgrade process is no longer possible if TPM2_FieldUpgradeDataVendor was successfully executed before (at least once).

***Note**: A dead time of 300 ms should be considered before sending the next command.*

Table 46 Incoming operands and sizes

Type	Name	Description
TPMI_ST_COMMAND_TAG	tag	TPM_ST_NO_SESSIONS
UINT32	commandSize	
TPM_CC	commandCode	TPM_CC_FieldUpgradeAbandonVendor
TPM2B_MAX_BUFFER	data	Optional data

Table 47 Outgoing operands and sizes

Type	Name	Description
TPM_ST	tag	

(table continues...)

Table 47 (continued) Outgoing operands and sizes

Type	Name	Description
UINT32	responseSize	
TPM_RC	responseCode	

Table 48 Error return codes

Return Code	Meaning
TPM_RC_COMMAND_SIZE	Incorrect command size
TPM_RC_BAD_TAG	Incorrect tag
TPM_RC_LOCALITY	The locality is not correct
RPM_RC_DISABLED	Abandon is not possible anymore
TPM_RC_FAILURE	The command failed

TPM2_GetCapability

While in TPM firmware update mode, this command can be used to read the TPM properties listed in Table 20 (except for TPM_PT_MODES) and vendor-specific properties shown in Table 22. The result is returned as TPML_MAX_BUFFER (see TPML_MAX_BUFFER for definition).

***Note**: In TPM firmware update mode, the TPM returns always only one single value at a time when TPM2_GetCapability is used. This deviates from the behavior when TPM2_GetCapability is used in normal TPM operational mode.*

TPM2_Selftest

In TPM firmware update mode this command can be used to execute on demand all selftests relevant for the field upgrade process, which are performed at first power-up. The selftest result can be read using the command TPM2_GetTestResult as described below.

Table 49 Incoming operands and sizes

Type	Name	Description
TPMI_ST_COMMAND_TAG	tag	TPM_ST_NO_SESSIONS
UINT32	commandSize	
TPM_CC	commandCode	TPM_CC_SelfTest

Table 50 Outgoing operands and sizes

Type	Name	Description
TPM_ST	tag	
UINT32	responseSize	
TPM_RC	responseCode	

TPM2_GetTestResult

In TPM firmware update mode, the TPM will return to the caller with outData = 11 bytes consisting of

- 4 bytes: a bit field describing the result of the passed selftests
- 4 bytes: a bit-field describing the not yet executed selftests
- 2 bytes: internal information
- 1 byte: operation mode (see Table 23)

The mapping of the individual bits to the corresponding selftest is shown in the table below (bit == 1 means that the test passed, RFU bits are reserved for future use).

Table 51 TPM2_GetTestResult bit mapping in TPM firmware update

Bit	Meaning	Bit	Meaning
31-22	RFU	15	Sensortest
21	ECDSA Verify P521 [1)]	14-7	RFU
20-19	RFU	6	SHA512
18	KDF AES256 CMAC	5	SHA384
17	AES256 ECB	4	SHA256
16	RFU	3-0	RFU

1) This selftest is only performed at first power up or if TPM2_SelfTest command is executed.

TPM2_Startup and TPM2_Shutdown

TPM2_Startup and TPM2_Shutdown are implemented, but only to satisfy requests of a host platform when TPM is in TPM firmware update mode. Both commands are not part of the authenticated field upgrade sequence and do not have any impact when called in the TPM firmware update mode.

3.2.7 Reset timing

The TPM_ACCESS_x.tpmEstablishment bit has the correct value and the TPM_ACCESS_x.tpmRegValidSts bit is set within 500 µs after RST# is deasserted.

***Note**: Access of any TPM SPI interface register is not allowed while RST# is asserted and within 500 µs after deassertion of RST#. If the TPM is in TPM firmware update mode, this time is 700 µs.*

The TPM typically is ready to receive a command after less than 50 ms in TPM operational mode.

***Note**: If the TPM is in TPM firmware update mode, the time until the TPM is ready to receive a command is 140 ms.*

If a TPM command is running, RST# should not be asserted; otherwise, this might also trigger some security functions. When the TPM shall be reset, the command TPM2_Shutdown should be issued before the assertion of the RST# signal.

3.2.8 Firmware version mapping

The TCG (see [1] and [2]) has defined two property tags for the reporting of the FW version (TPM_PT_FIRMWARE_VERSION_1 and TPM_PT_FIRMWARE_VERSION_2). TPM_PT_FIRMWARE_VERSION_1 is clearly defined to report the major firmware version in the upper 16 bits and the minor firmware version in the lower 16 bits. For TPM_PT_FIRMWARE_VERSION_2 there is no definition except that this field may be used as an extension to TPM_PT_FIRMWARE_VERSION_1. Therefore, interpretation of TPM_PT_FIRMWARE_VERSION_2 may lead to different results based on different definitions of this field. The following table provides a mapping between the definition of TPM_PT_FIRMWARE_VERSION_2 for SLB 9672 TPM 2.0 FW15.xx and the interpretation of TPM_PT_FIRMWARE_VERSION_2 as if this field was defined as two 16 bit values (like TPM_PT_FIRMWARE_VERSION_1).

Table 52 Definition of the firmware version fields

	TPM_PT_FIRMWARE_VERSION_1		TPM_PT_FIRMWARE_VERSION_2		
Infineon	MM	mm	0x00	bb	Cert. state
Alternative	MM	mm	BB	bb	

***Note**: MM = Major firmware version*
mm = Minor firmware version
BB = Major build number
bb = Minor build number (or just build number for Infineon)
Cert. State = Common Criteria certification state (see Table 20)

Table 53 Mapping of the firmware versions

Infineon	Alternative	Firmware Version 1	Firmware Version 2
15.12.15679.02	15.12.3D.3F02	0x000F000C	0x003D3F02
15.20.15686.00	15.20.3D.4600	0x000F0014	0x003D4600
15.21.16430.00	15.21.40.2E00	0x000F0015	0x00402E00
15.22.16832.00	15.22.41.C000	0x000F0016	0x0041C000
15.23.17664.00	15.23.45.0000	0x000F0017	0x00450000
15.24.18954.00	15.24.4A.0A00	0x000F0018	0x004A0A00

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References

[1] TCG: *"Trusted Platform Module Library (Part 1-4)", Family 2.0, Level 00, Rev. 01.59*; November 8, 2019

[2] TCG: *"TCG PC Client Platform TPM Profile Specification for TPM 2.0", Version 1.05, Revision 14*; September 4, 2020

[3] TCG: *"Errata for TCG Trusted Platform Module Library, Family 2.0, Level 00, Rev. 01.59, November 8, 2019", Errata Version 1.5*; January 25, 2024

[4] TCG: *"Errata for PC Client Platform TPM Profile for TPM 2.0 Version 1.05 Revision 14", Errata Version 1.2*; February 2, 2024

[5] TCG: *"Registry of reserved TPM 2.0 handles and localities", Version 1.1, Rev. 1.00*; February 6, 2019

[6] TCG: *"TCG EK Credential Profile", Version 2.3, Rev. 2*; July 23, 2020

[7] NIST: *"NIST Special Publication 800-193, Platform Firmware Resiliency Guidelines"*; May 2018

Revision history

Document version	Date of release	Description of changes
Revision 1.5	2024-11-17	• New document layout with reordered content • Added section TPM embedded software • Changed some wording in Key features section (and whole document where applicable) • Changed wording in Product description • Updated name of referenced TCG PTP spec [2] • Removed 0x60 and 0x61 in TPM and vendor properties • Updated reference [3] • Updated reference [4] • Fixed various typos
Revision 1.4	2024-04-19	Updated build number in TPM and vendor properties
Revision 1.3	2024-01-31	• Changed SCLK slew rate parameter in Table 9 • Updated version and build numbers in TPM and vendor properties • Added recommendation to connect unused pins in Table 13 • Updated reset timing in Figure 5 • Added details on datecode to Chip marking
Revision 1.2	2023-04-27	• Added features to front page • Fixed wrong revision number in Product description • Changed Figure 7 (additional decoupling capacitor) • Updated version and build numbers in TPM and vendor properties • Minor editorial changes
Revision 1.1	2022-01-20	• Changed Figure 7 added to pull-up resistor
Revision 1.0	2022-01-12	• Initial document version

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